

L Number	Hits	Search Text	DB	Time stamp
2	59826	bond\$3 with (wir\$3 interconnect\$3)	USPAT;	2004/05/14 12:38
4	38021	((bond\$3 with (wir\$3 interconnect\$3)) and (remov\$3 detach\$3))	US-PGPUB	2004/05/14 12:21
5	15665	((bond\$3 with (wir\$3 interconnect\$3)) and (remov\$3 detach\$3)) and (light x?ray x-ray ("x" near3 "ray"))	USPAT;	2004/05/14 12:22
6	8767	((bond\$3 with (wir\$3 interconnect\$3)) and (remov\$3 detach\$3)) and (light x?ray x-ray ("x" near3 "ray")) and ((second dummy sacrificial temp\$8) near50 (base substrate wafer))	US-PGPUB	2004/05/14 12:22
7	6766	((bond\$3 with (wir\$3 interconnect\$3)) and (remov\$3 detach\$3)) and (light x?ray x-ray ("x" near3 "ray")) and ((second dummy sacrificial temp\$8) near50 (base substrate wafer)) and (insulat\$3 dielectric)	USPAT;	2004/05/14 12:19
8	50503	((bond\$3 with (wir\$3 interconnect\$3)) and (remov\$3 detach\$3 separat\$5))	US-PGPUB	2004/05/14 12:38
9	19768	((bond\$3 with (wir\$3 interconnect\$3)) and (remov\$3 detach\$3 separat\$5)) and (light x?ray x-ray ("x" near3 "ray"))	USPAT;	2004/05/14 12:38
10	10522	((bond\$3 with (wir\$3 interconnect\$3)) and (remov\$3 detach\$3 separat\$5)) and (light x?ray x-ray ("x" near3 "ray")) and ((second dummy sacrificial temp\$8) near50 (base substrate wafer))	US-PGPUB	2004/05/14 12:23
11	1811	((bond\$3 with (wir\$3 interconnect\$3)) and (remov\$3 detach\$3 separat\$5)) and (light x?ray x-ray ("x" near3 "ray")) and ((second dummy sacrificial temp\$8) near50 (base substrate wafer)) and ((heat\$3 irrads\$6) same (remov\$3 detach\$3 separat\$5) same (second dummy sacrificial temp\$8) same (base substrate wafer))	USPAT;	2004/05/14 12:39
12	53946	bond\$3 with (wir\$3 interconnect\$3)	EPO; JPO; DERWENT; IBM_TDB	2004/05/14 12:38
13	6594	((bond\$3 with (wir\$3 interconnect\$3)) and (remov\$3 detach\$3 separat\$5))	EPO; JPO; DERWENT; IBM_TDB	2004/05/14 12:38
14	434	((bond\$3 with (wir\$3 interconnect\$3)) and (remov\$3 detach\$3 separat\$5)) and (light x?ray x-ray ("x" near3 "ray"))	EPO; JPO; DERWENT; IBM_TDB	2004/05/14 12:39
15	13	((bond\$3 with (wir\$3 interconnect\$3)) and (remov\$3 detach\$3 separat\$5)) and (light x?ray x-ray ("x" near3 "ray")) and ((heat\$3 irrads\$6) same (remov\$3 detach\$3 separat\$5) same (second dummy sacrificial temp\$8) same (base substrate wafer))	EPO; JPO; DERWENT; IBM_TDB	2004/05/14 12:39